



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

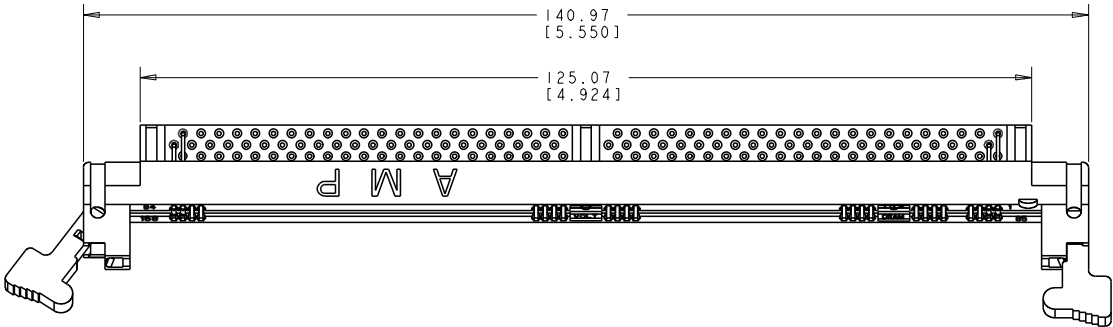
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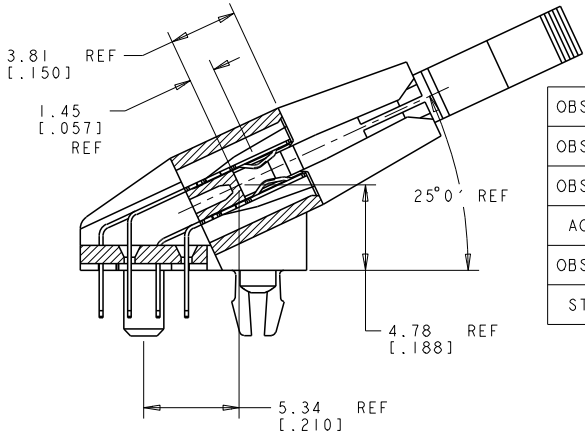
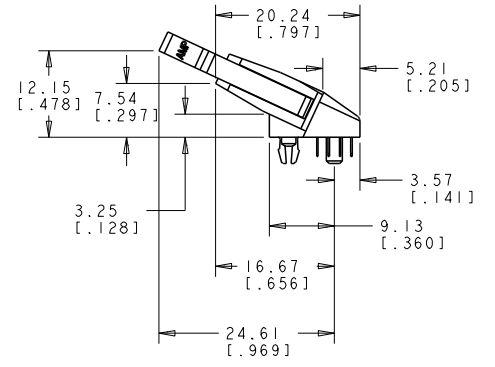
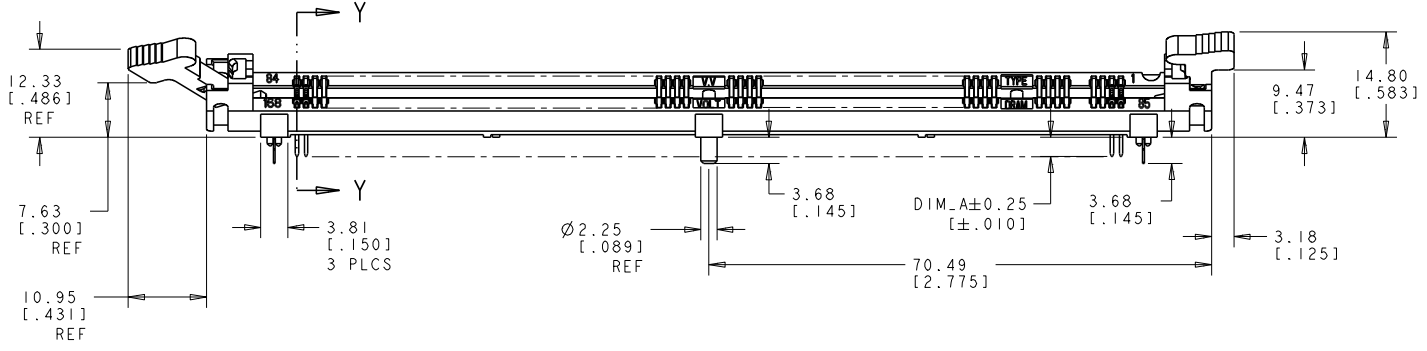


LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	OWN	APVD
		A		RELEASED PER 0S12-0488-04	30NOV04	MY	MY
		D		REVISED PER ECR-10-005884	22MAR2010	FC	SY



- NOTES:
- MATERIAL:
HOUSING AND EJECTOR:
HIGH TEMPERATURE NYLON
CONTACT:
PHOSPHOR BRONZE
 - FINISH:
CONTACT AREA:
0.00076[.000030] MIN THICK GOLD OVER
0.00127[.000050] MIN THICK NICKEL
SOLDERTAIL:
0.0038[.000150] MIN THICK MATTE TIN OVER
0.00064[.000025] MIN THICK NICKEL
 - MODULE BOARD PADS:
FOR OPTIMUM PERFORMANCE PADS SHOULD BE SMOOTH AND FLAT
PADS TO BE PLATED WITH:
0.00102[.000040] MIN THICK GOLD OVER
0.00127[.000050] MIN THICK NICKEL

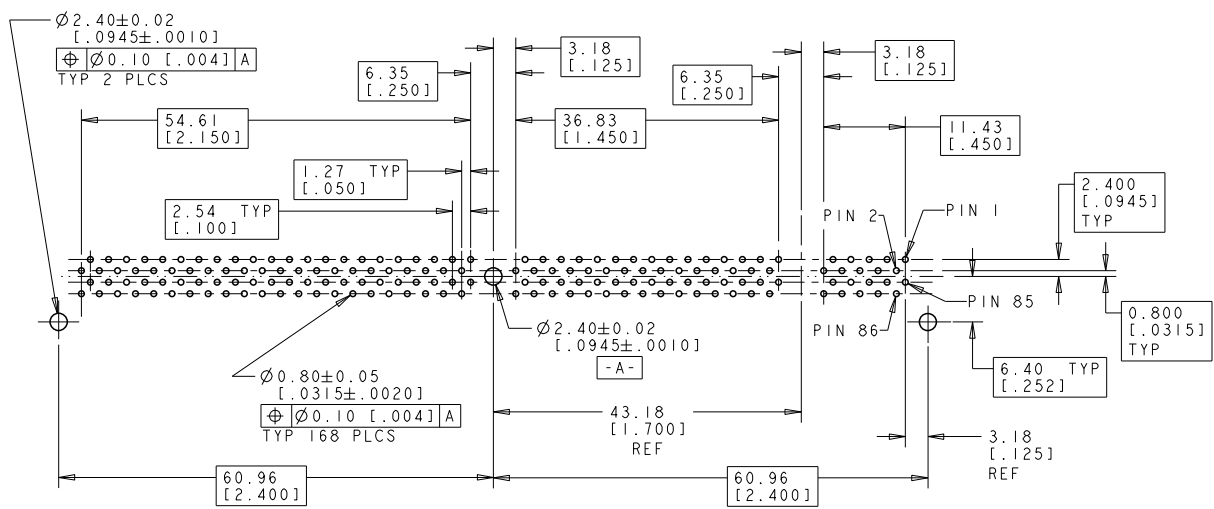
- △4 WAVE SOLDER COMPATIBLE.
- △5 REFLOW COMPATIBLE.
- △6 PARTS ARE PACKAGED IN TUBES.



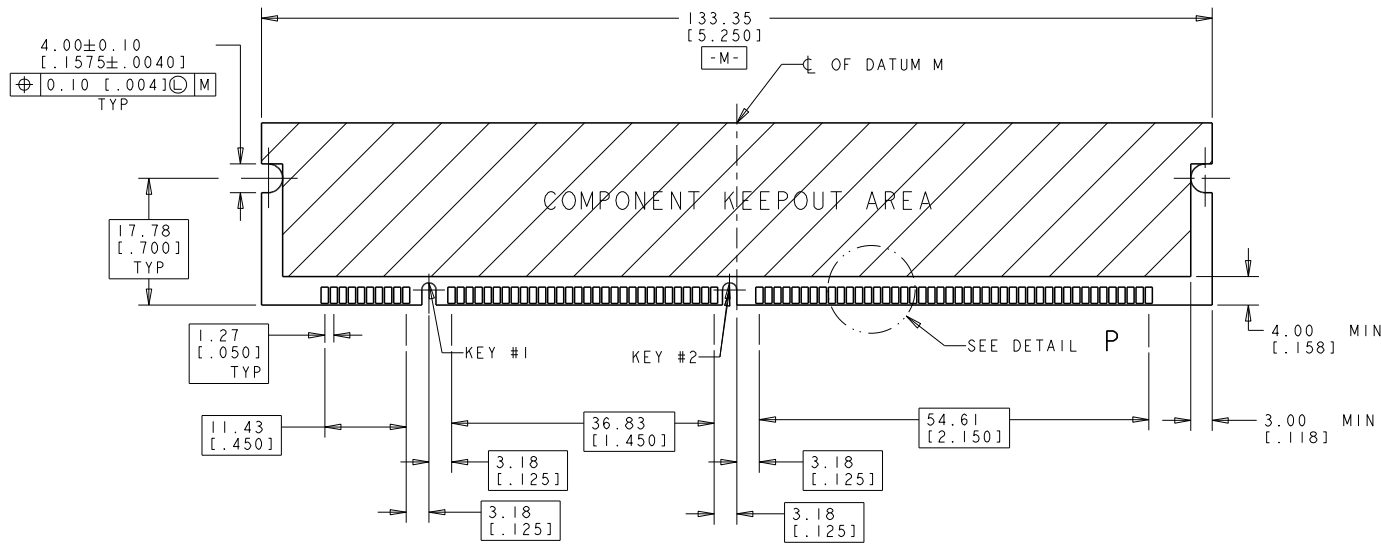
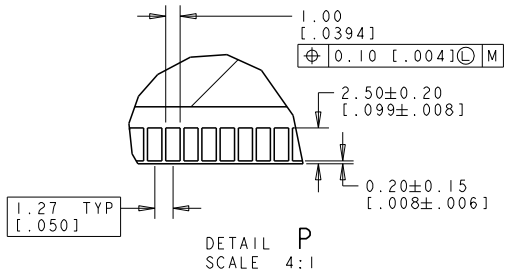
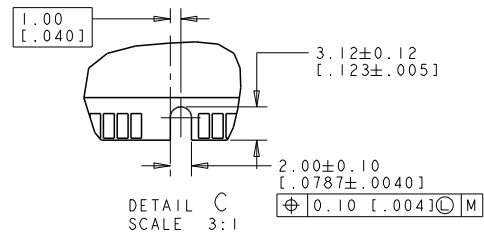
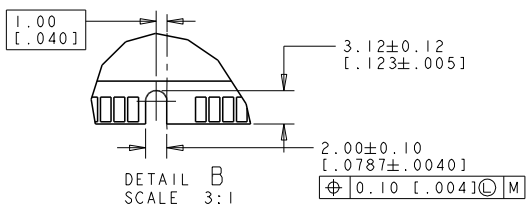
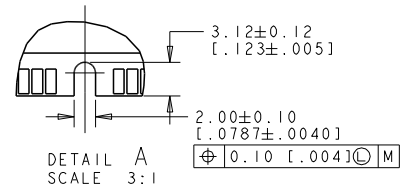
OBSOLETE	4.50 [.177]	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	3-5390185-6 △4
OBSOLETE	3.18 [.125]	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	2-5390185-6 △6
OBSOLETE	3.18 [.125]	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	1-5390185-6 △5
ACTIVE	3.18 [.125]	DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	5390185-6 △4
OBSOLETE	3.18 [.125]	DETAIL A	DETAIL A	STD DRAM, 3.3 VOLT	5390185-4
STATUS	SOLDERTAIL LENGTH DIM_A	KEY #1	KEY #2	PART DESCRIPTION	PART NUMBER

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION. IT IS SUBJECT TO CHANGE AND THE COMPANY, IN THE ENTIRE ORGANIZATION, SHOULD BE CONTACTED FOR THE LATEST INFORMATION.</small>		DWN M. YEOMANS 30NOV04 CHK M. YEOMANS 30NOV04 DWN M. YEOMANS 30NOV04 REV M. YEOMANS 30NOV04	tyco Electronics Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.131(.005) 3 PLC ± 4 PLC ± ANGLES ± FINISH	NAME PRODUCT SPEC APPLICATION SPEC WEIGHT CUSTOMER DRAWING	NAME SOCKET ASSEMBLY, 168 POSITION, CENTER PLASTIC POST LOW PROFILE DIMM 2 P, LEAD-FREE SIZE CAGE CODE DRAWING NO A200779 C=5390185 RESTRICTED TO SCALE 2:1 SHEET 1 OF 3 REV D

LOC	DIST	REVISIONS					
GP	00	REV	LYR	DESCRIPTION	DATE	OWN	APVD
		-		SEE SHEET 1			



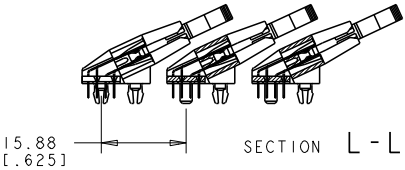
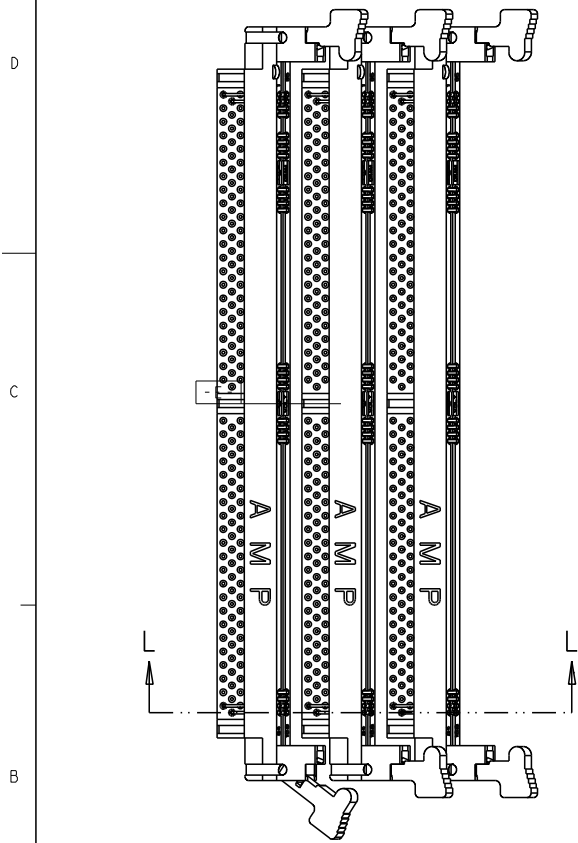
RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



RECOMMENDED MODULE LAYOUT
 SEE JEDEC SPEC. MO-161 FOR COMPLETE MODULE DETAILS
 1.27±0.10 [.050±.004] THICK ACROSS CONTACT PADS

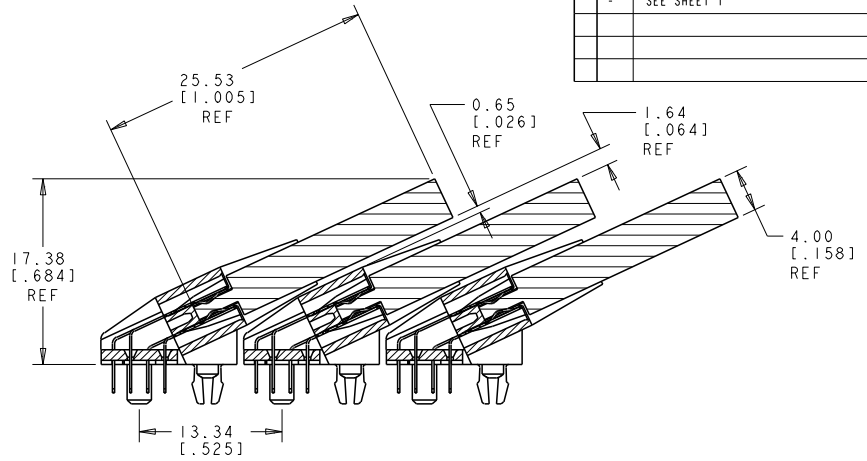
<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION. IT IS SUBJECT TO CHANGE AND THE USER SHALL CONTACT THE DRAWING ORGANIZATION PRIOR TO CONTACT FOR THE LATEST REVISION.</small>		DWN M. YEFOMANS 30NOV04 CHK M. YEFOMANS 30NOV04 DWN M. YEFOMANS 30NOV04 APVD M. YEFOMANS 30NOV04	tyco Electronics Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.131(.005) 3 PLC ± 4 PLC ± ANGLES ± FINISH	NAME SOCKET ASSEMBLY, 168 POSITION, CENTER PLASTIC POST LOW PROFILE DIMM 2 P, LEAD-FREE	SIZE CAGE CODE DRAWING NO A 200779 C=5390185
MATERIAL	WEIGHT	APPLICATION SPEC	RESTRICTED TO
CUSTOMER DRAWING		SCALE 2:1	SHEET 2 OF 3 REV D

LOC	DIST	REVISIONS					
GP	00	P	LTR	DESCRIPTION	DATE	OWN	APVD
		-		SEE SHEET 1			



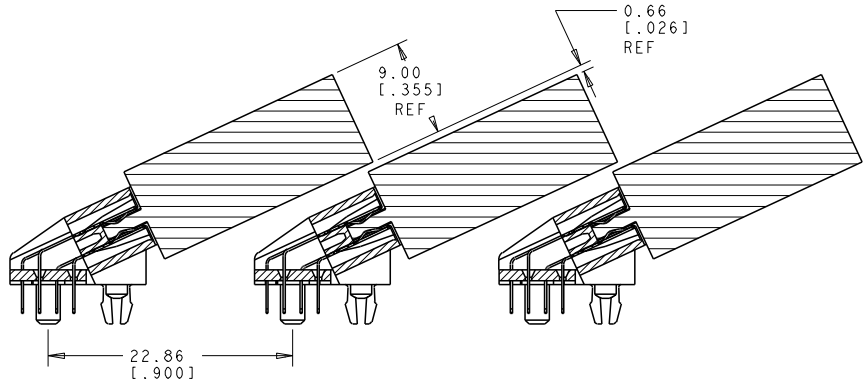
MINIMUM REPAIRABLE
 SOCKET TO SOCKET SPACING

WITH THE MODULES REMOVED, SOCKETS ON 15.88 [.625] OR GREATER SPACING CAN BE INDIVIDUALLY UNSOLDERED FROM THE BOARD AND REMOVED IF NECESSARY.



MINIMUM SOCKET TO SOCKET SPACING

WITH A 4.00 [.158] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 [.525] WILL LEAVE APPROXIMATELY 0.65 [.026] OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



POSSIBLE SOCKET TO SOCKET SPACING FOR 9MM SOCKET

WITH A 9.00 [.355] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 22.86 [.900] WILL LEAVE APPROXIMATELY 0.66 [.026] CLEARANCE BETWEEN THE ADJACENT MODULES. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROL BY THE ISSUING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISIONS</small>		DWN M. YEFOMANS 30NOV04 CHK M. YEFOMANS 30NOV04 DWN M. YEFOMANS 30NOV04	tyco Electronics Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.131(.005) 3 PLC ± ANGLES ± FINISH	NAME M. YEFOMANS 30NOV04 PRODUCT SPEC APPLICATION SPEC WEIGHT CUSTOMER DRAWING	SOCKET ASSEMBLY, 168 POSITION, CENTER PLASTIC POST LOW PROFILE DIMM 2 P, LEAD-FREE SIZE CAGE CODE DRAWING NO RESTRICTED TO A 200779 C=5390185
MATERIAL		SCALE 2:1 SHEET 3 OF 3 REV D	

5390185